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Date: 03	3/02/2012					
	PI	MP7390B B	OM			
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			Description	Size	Part Number	MFR
	C14	22pF	Capacitor, Ceramic Chip, 25V, X7R, 10%	0402	Std	Std
	C16	470pF	Capacitor, Ceramic Chip, 25V, X7R, 10%	0402	Std	Std
	C8	1000pF	Capacitor, Ceramic Chip, 50V, X7R, 10%	0402	Std	Std
	C15	3300pF	Capacitor, Ceramic Chip, 25V, X7R, 10%	0402	Std	Std
	C10, C17, C18	0.1uF	Capacitor, Ceramic Chip, 25V, X7R, 10%	0402	Std	Std
-	C13	0.33uF	Capacitor, Ceramic Chip, 16V, X5R, 20%	0402	Std	Std
	C12	1uF	Capacitor, Ceramic Chip, 16V, X5R, 20%	0402	Std	Std
	C11	1uF	Capacitor, Ceramic Chip, 50V, X7R, 10%	0805	Std	Std
	C1, C2, C3	4.7uF	Capacitor, Ceramic Chip, 50V, X7R, 10%	1206	Std	Std
1	C9	10uF	Capacitor, Ceramic Chip, 16V, X7R, 10%	0603	Std	Std
4	C4, C5, C6	22uF	Capacitor, Ceramic Chip, 6.3V, X5R, 20%	0805	Std	Std
2	J1, J2	690-004-261-013	Connector, USB A Type	0.298 X 0.55 Inch	690-004-261-013	EDAC
1	L1	10uH	Inductor, Powdered Iron, 28mohm, 7.5A	0.400 x 0.453 inch	IHLP4040DZER100M11	Vishay
	Q1, Q2	FDS5351	MOSFET, N-ch, 60-V, 6.1-A, 42-milliOhms	SO8	FDS5351	Fairchild
	R2, R3	0	Resistor, Chip, 1/16W, 1%	0402	Std	Std
	R12	49.9	Resistor, Chip, 1/16W, 1%	0402	Std	Std
	R10	2.00K	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R8	6.65K	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R4	10.0K	Resistor, Chip, 1/16W, 1%	0402	Std	Std
2	R15, R18	16.9K	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R9	20.0K	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R5	31.6K	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R1	40.2K	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R11	49.9K	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R6	100K	Resistor, Chip, 1/16W, 1%	0402	Std	Std
2	R14, R17	200K	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R7	499K	Resistor, Chip, 1/16W, 1%	0402	Std	Std
4	TP3, TP5	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
2	TP4, TP6	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	U1	TPS40170RGY	IC, 4.5V - 60V Wide Input Sync. PWM Buck Controller	QFN-20	TPS40170RGY	ΤI
			IC, INTELLIGENT USB CHARGING CONTROLLER		-	1
2	U2, U3	TPS2511DGN	WITH CURRENT LIMITING POWER SWITCH	HTSSOP	TPS2511DGN	ті

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